RELIABILITY REPORT
FOR
MAX294CPA+
PLASTIC ENCAPSULATED DEVICES

December 23, 2008

MAXIM INTEGRATED PRODUCTS
120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
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Quality Assurance
Director, Reliability Engineering
Conclusion

The MAX294CPA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim’s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim’s quality and reliability standards.

Table of Contents

I. Device Description
   A. General

II. Manufacturing Information

III. Packaging Information

IV. Die Information

V. Quality Assurance Information

VI. Reliability Evaluation

.....Attachments

See Data Sheet
II. Manufacturing Information

A. Description/Function: 8th-Order, Lowpass, Elliptic, Switched-Capacitor Filters
B. Process: S3
C. Number of Device Transistors: 
D. Fabrication Location: Oregon
E. Assembly Location: Hana Thailand, Carsem Malaysia, UTL Thailand
F. Date of Initial Production: Pre 1997

III. Packaging Information

A. Package Type: 8-pin PDIP
B. Lead Frame: Copper
C. Lead Finish: 100% matte Tin
D. Die Attach: Conductive Epoxy
E. Bondwire: Gold (1.3 mil dia.)
F. Mold Material: Epoxy with silica filler
G. Assembly Diagram: #05-0201-0111
H. Flammability Rating: Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C Level 1
J. Single Layer Theta Ja: 110°C/W
K. Single Layer Theta Jc: 40°C/W

IV. Die Information

A. Dimensions: 89 X 95 mils
B. Passivation: Si3N4/SiO2 (Silicon nitride/ Silicon dioxide
C. Interconnect: Aluminum/Si (Si = 1%)
D. Backside Metallization: None
E. Minimum Metal Width: 3.0 microns (as drawn)
F. Minimum Metal Spacing: 3.0 microns (as drawn)
G. Bondpad Dimensions: 5 mil. Sq.
H. Isolation Dielectric: SiO2
I. Die Separation Method: Wafer Saw
V. Quality Assurance Information

A. Quality Assurance Contacts: Ken Wendel (Director, Reliability Engineering)  
   Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
   0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

   The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ($\lambda$) is calculated as follows:

   \[ \lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \]  
   (Chi square value for MTTF upper limit)

   (where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

   \[ \lambda = 13.4 \times 10^{-9} \]

   \[ \lambda = 13.4 \text{ F.I.T. (60% confidence level @ 25°C)} \]

   The following failure rate represents data collected from Maxim’s reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/.  
   Current monitor data for the S3 Process results in a FIT Rate of 3.6 @ 25C and 66.0 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

   The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

   The AF11-6 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-100 mA.
### Table 1
Reliability Evaluation Test Results

<table>
<thead>
<tr>
<th>TEST ITEM</th>
<th>TEST CONDITION</th>
<th>FAILURE IDENTIFICATION</th>
<th>SAMPLE SIZE</th>
<th>NUMBER OF FAILURES</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Static Life Test</strong>  (Note 1)</td>
<td>Ta = 135°C Biased Time = 192 hrs.</td>
<td>DC Parameters &amp; functionality</td>
<td>80</td>
<td>0</td>
</tr>
<tr>
<td><strong>Moisture Testing</strong>  (Note 2)</td>
<td>85/85 Ta = 85°C RH = 85% Biased Time = 1000hrs.</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
<tr>
<td><strong>Mechanical Stress</strong>  (Note 2)</td>
<td>Temperature Cycle Method 1010</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
</tbody>
</table>

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data